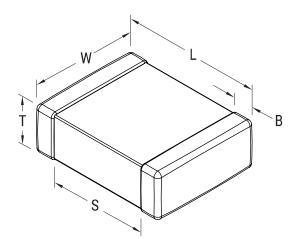


C0603C153G3TAC7411

SMD Comm X8G HT150C, Ceramic, 0.015 uF, 2%, 25 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

Dimensions		s
Chip Size	0603	C
L	1.6mm +/-0.15mm	Ν
W	0.8mm +/-0.15mm	Т
т	0.8mm +/-0.07mm	V
S	0.5mm MIN	C
В	0.35mm +/-0.15mm	Т
		т

Packaging Specifications T&R, 330mm, Paper Tape Packaging Pac

citaging	ran, ooonnin, raper rape
ckaging Quantity	15000

Specifications	
Capacitance	0.015 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	2%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	66.6667 GOhms

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